

Financial Results Briefing Material

for the First Quarter of the Fiscal Year Ending March 2024

JCU CORPORATION

TSE Prime (Stock Code: 4975)

August 3, 2023



Chemicals **Business**

Machine Business

Summary of Consolidated Financial Results for 1Q FY3/24



Accounting Period of 1Q FY3/24

JCU (non-consolidated): April 1 to June 30, 2023

Overseas subsidiaries: January 1 to March 31, 2023

For electronic components

For automotive components

■ China: Due to the stagnation of consumer spending and the ending of stay-at-home demand, demand for PWBs for high-performance electronic devices such as smartphones, PCs, and tablets decreased. As a result, sales of chemicals decreased.

- Taiwan: Due to a decrease in demand for PWBs for high-performance electronic devices, servers, and semiconductor package substrates for high-performance electronic devices, sales of chemicals decreased.
- South Korea: Due to the continued impact of inventory adjustment in the semiconductor market, demand for semiconductor package substrates decreased. As a result, sales of chemicals decreased.
- Japan: The improving trend in shortages of semiconductors and parts led to a recovery in domestic automobile production and an increase in sales of chemicals.
- China: Despite a recovery trend in shortages of semiconductors and parts, the automobile sales and production decreased due to decelerating economies. As a result, sales of chemicals decreased.

Net sales, orders received, and order backlog increased substantially thanks to the resumption of the projects that had been postponed due to the pandemic and the steady progress of ongoing construction projects.

Summary of Financial Results for 1Q FY3/24



(Millions of yen)

	Same period of previous FY (1Q FY3/23)	1Q FY3/24	YoY % Change
Net sales	6,160	5,225	(15.2)%
Operating profit	2,020	1,379	(31.7)%
Ordinary profit	2,206	1,383	(37.3)%
Profit attributable to owners of parent	1,607	944	(41.2)%
Net income per share	61.97 yen	36.85 yen	-

Foreign Exchange Rates



Foreign exchange sensitivity (as at the consolidated year): Changes of about 105 million yen in consolidated operating profit with 1% change in major currency rates listed below

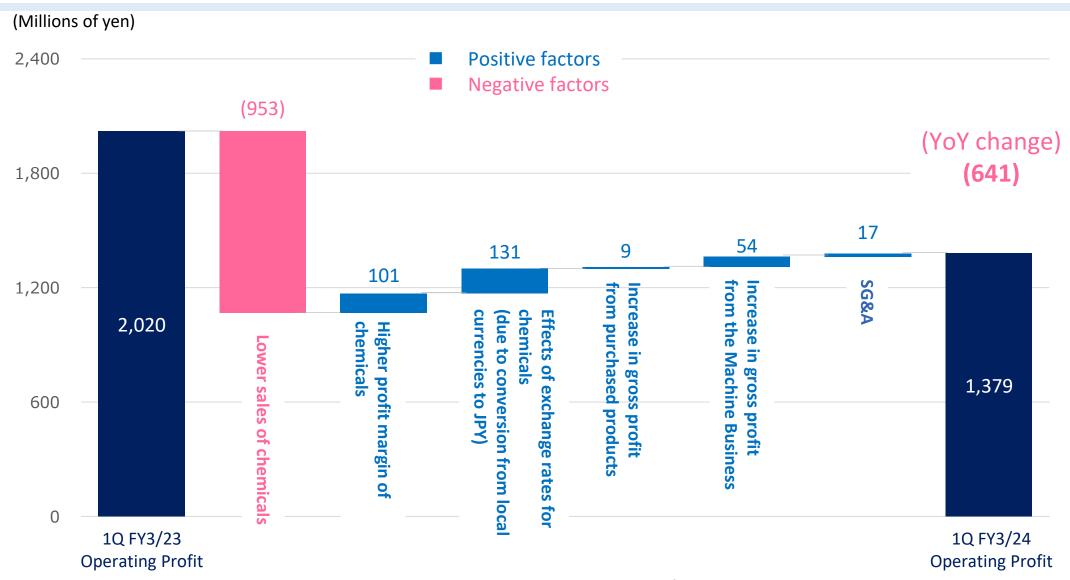
(Yen)

	FY3/23			FY3/24	
	1Q	2Q	3Q	4Q	1Q (Initial forecast)
Chinese yuan (CNY)	18.29	18.93	19.35	19.48	19.34
Taiwan dollar (TWD)	4.15	4.28	4.37	4.41	4.36
Korean won (KRW)	0.0964	0.0996	0.1008	0.1017	0.1039

Note: The average rate for the period is used to translate Chinese yuan, Taiwan dollar and Korean won, our major foreign currencies, to Japanese yen.

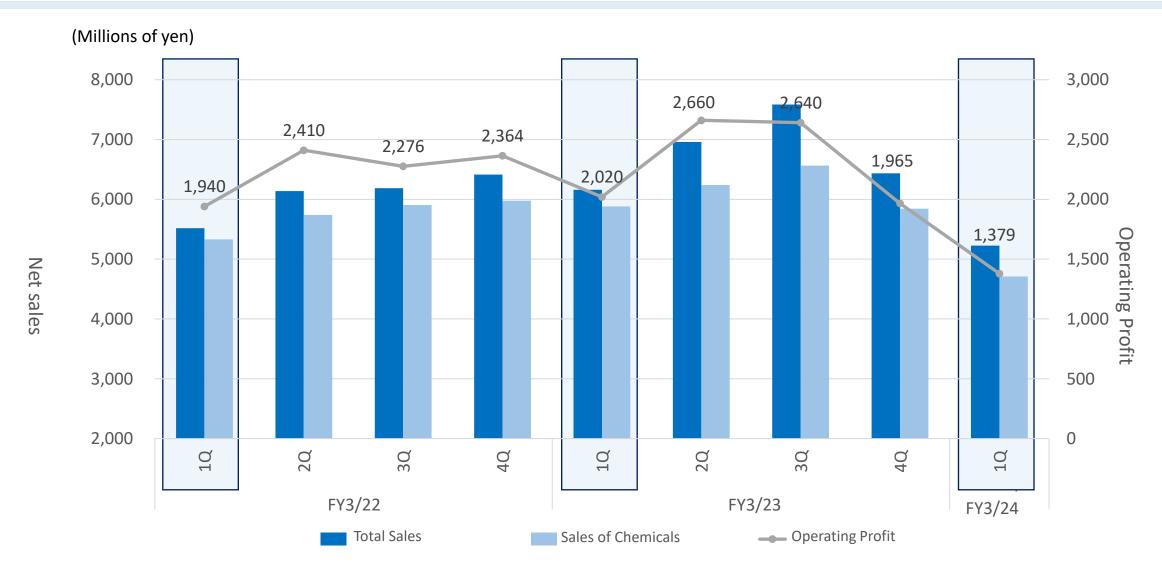
Changes in Consolidated Operating Profit for 1Q FY3/24





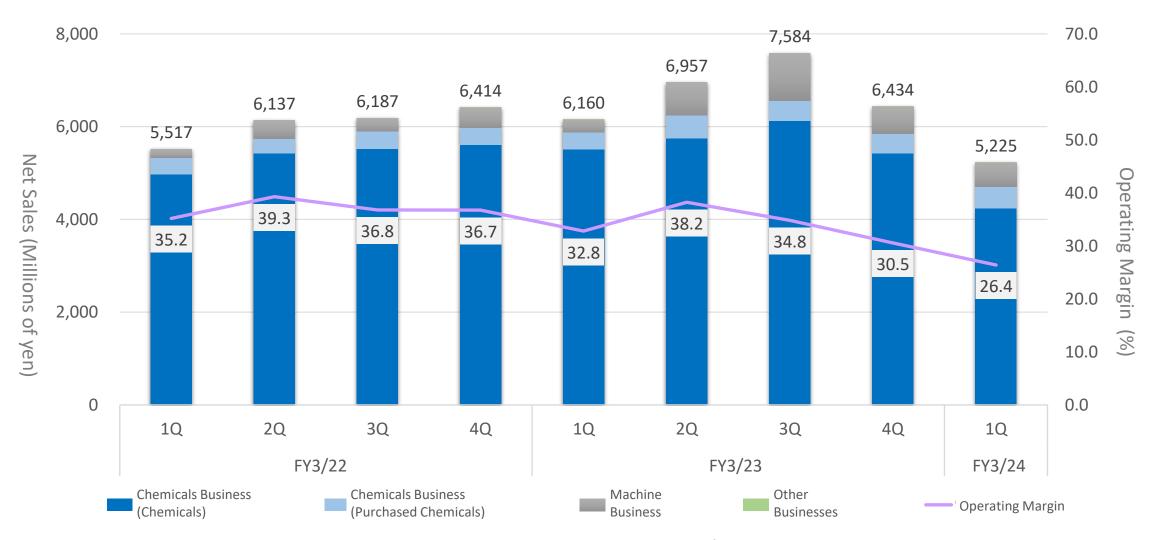
Quarterly Consolidated Financial Results





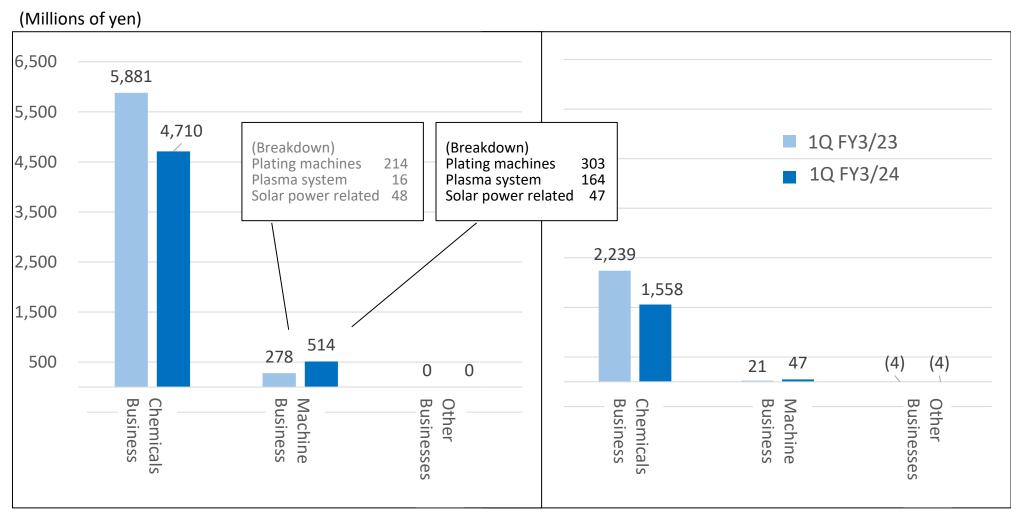
Quarterly Consolidated Financial Results (By Segment)





Consolidated Segment Results for 1Q FY3/24



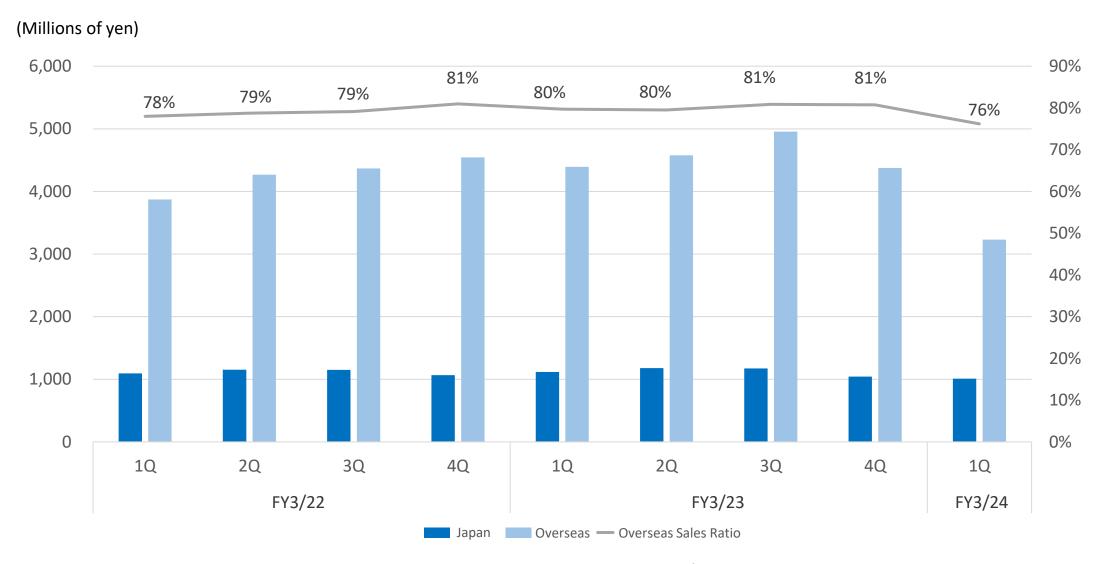


Net Sales

Segment Profit (Loss)

Quarterly Sales of Chemicals in Japan and Overseas

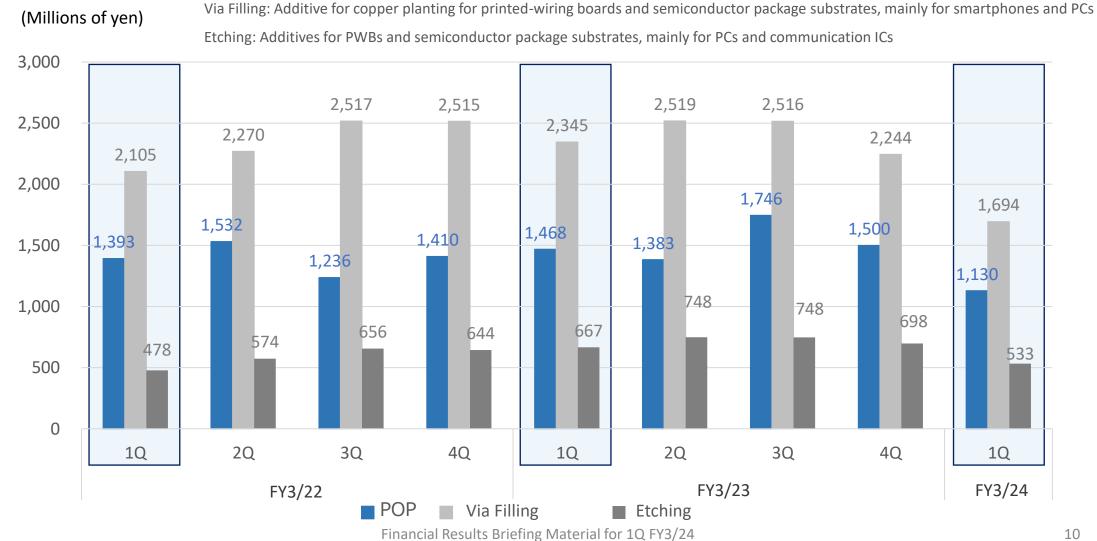




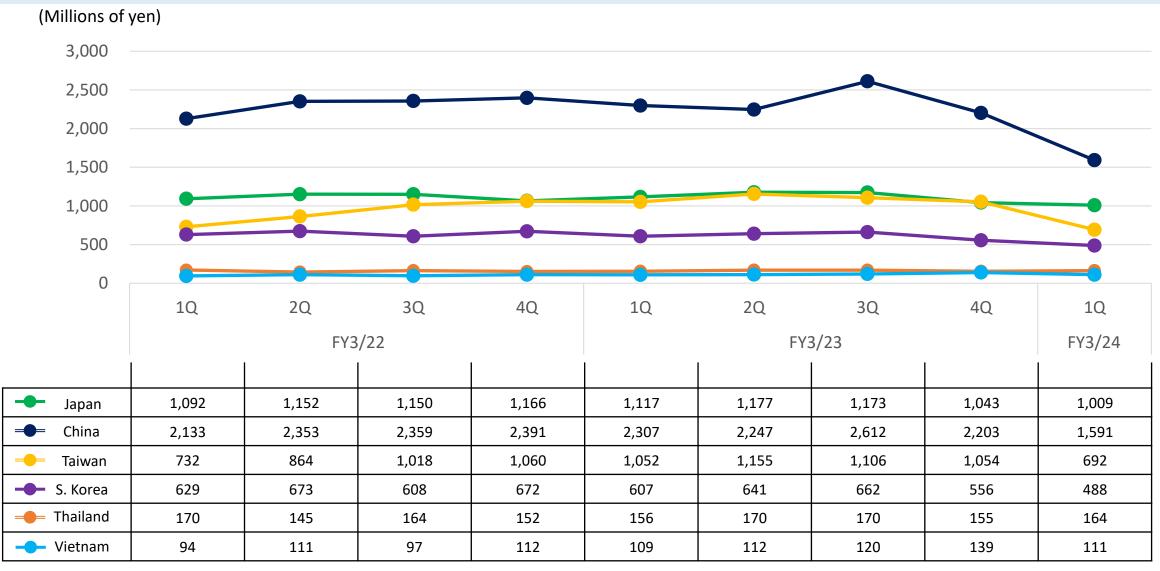
Chemicals, POP, Via Filling and Etching | Quarterly Sales



POP: Planting on Plastics, mainly for automotive components

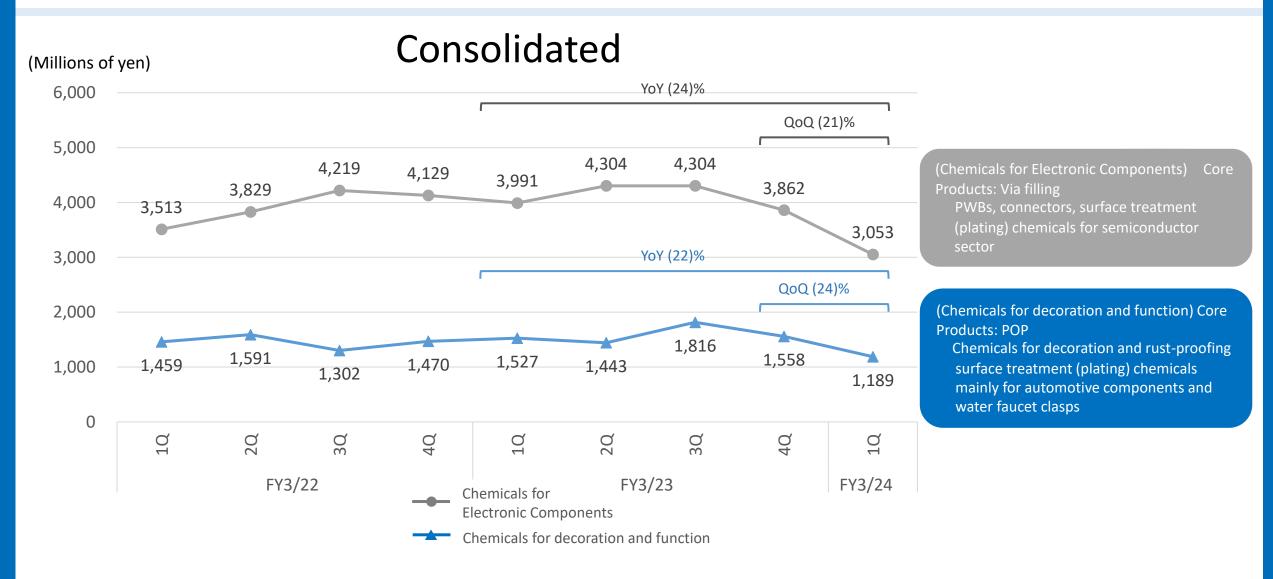




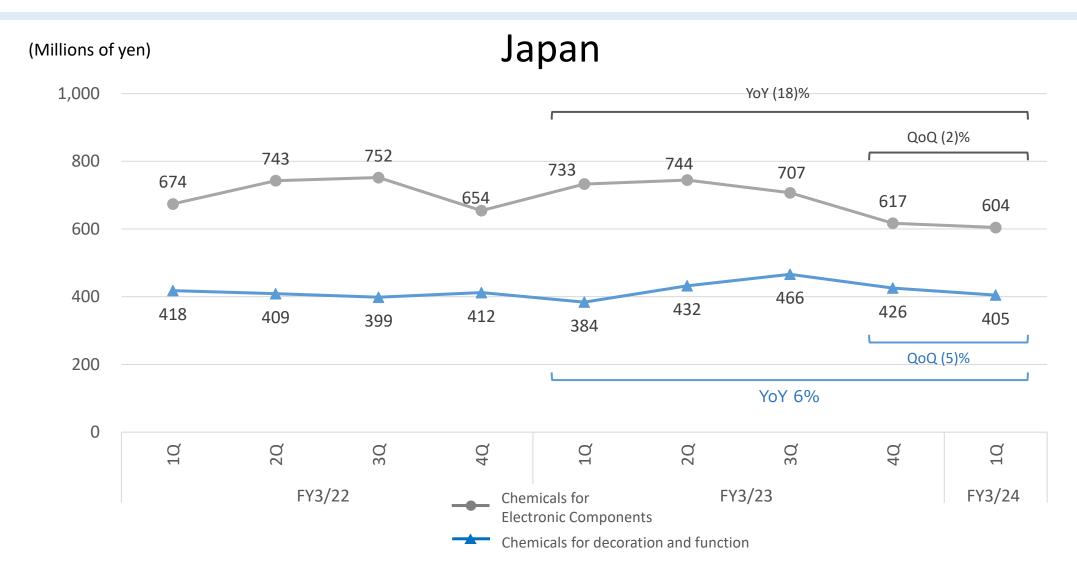


Quarterly Sales of Chemicals by Category

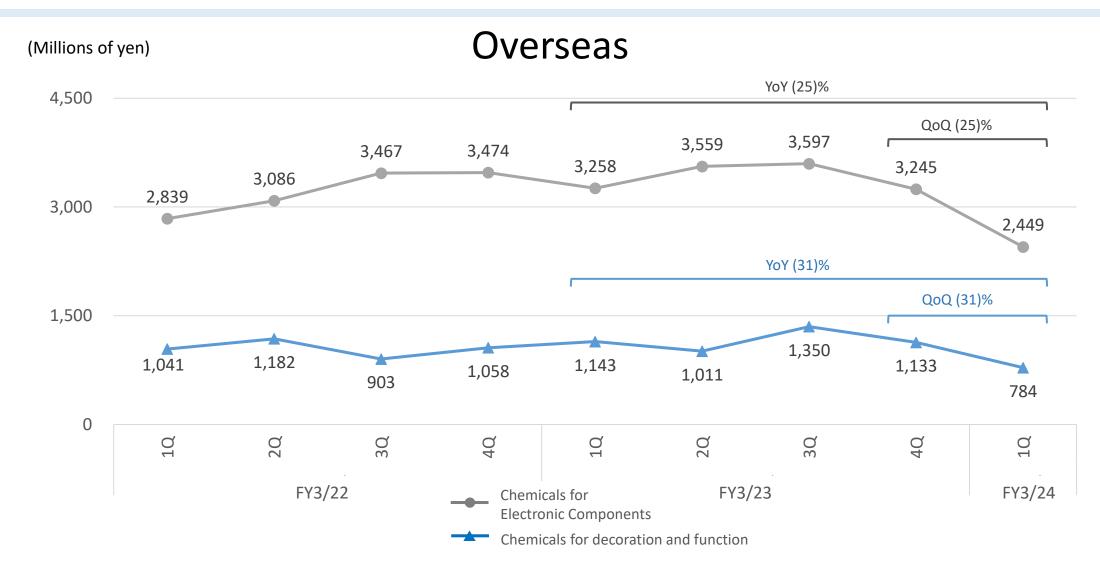




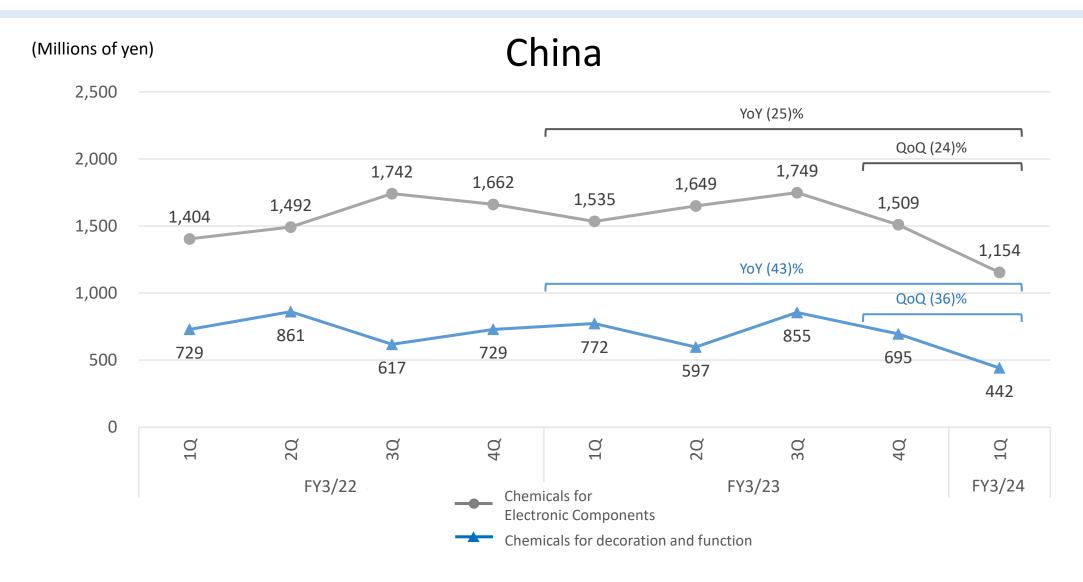




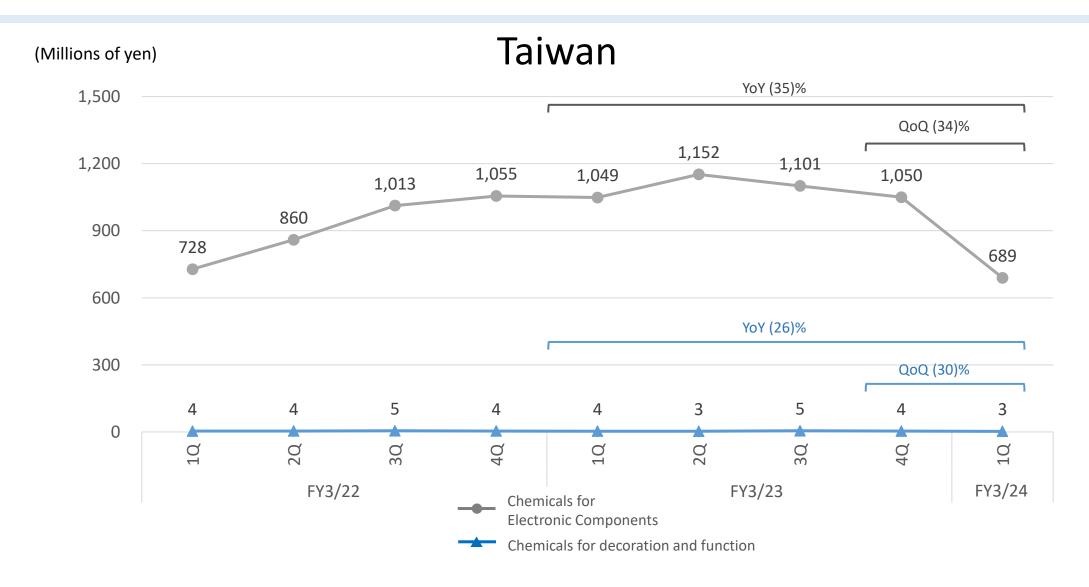




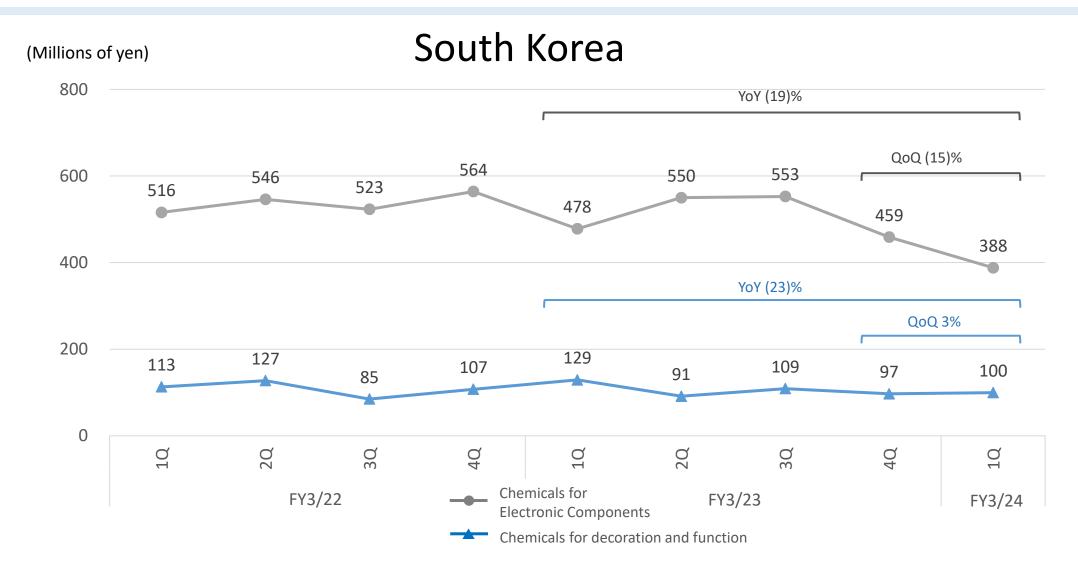












Forecasts for FY3/24

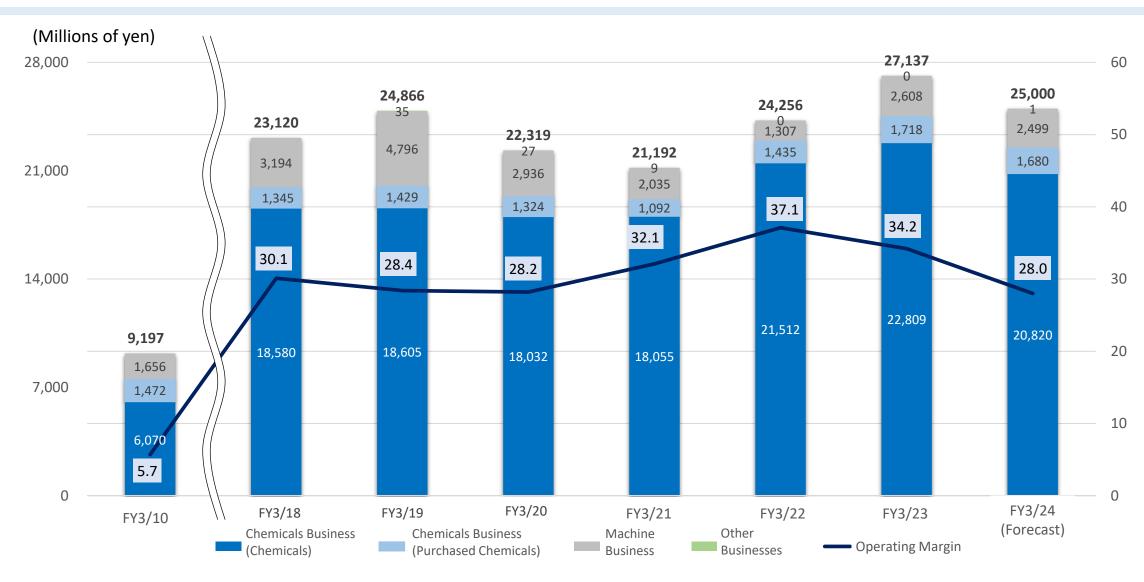


(Millions of yen)

FY3/24	1Q (Results)	1H (Forecasts)	Full year (Forecasts)	Progress rate against full- year forecast
Net sales	5,225	10,700	25,000	20.9%
Operating profit	1,379	2,590	7,000	19.7%
Ordinary profit	1,383	2,590	7,000	19.8%
Profit attributable to owners of parent	944	1,750	4,800	19.7%
Net income per share	36.85 yen	68.29 yen	187.30 yen	-

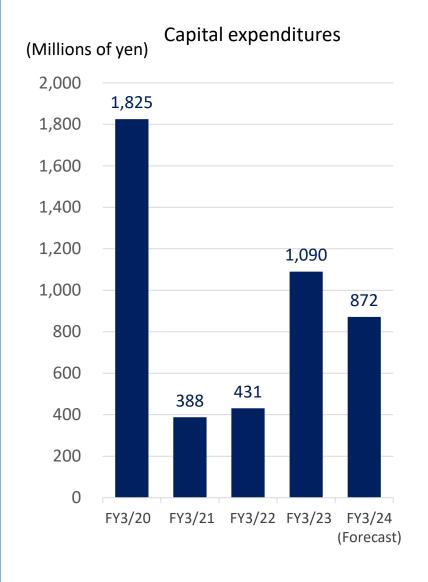
Annual Sales by Business (incl. Forecast)

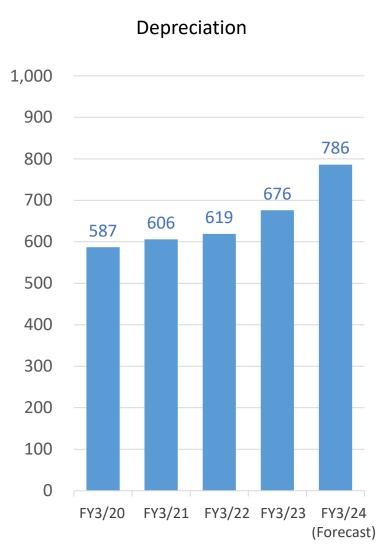


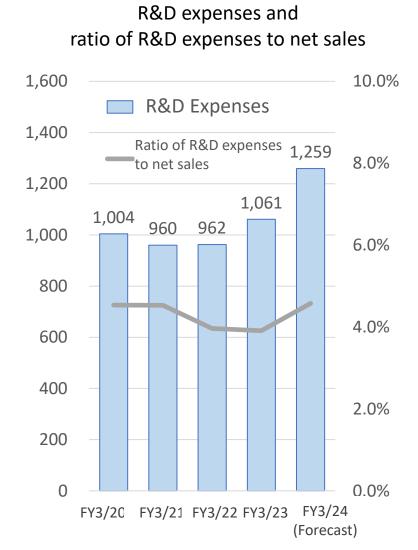


Capital Expenditures, Depreciation and R&D Expenses



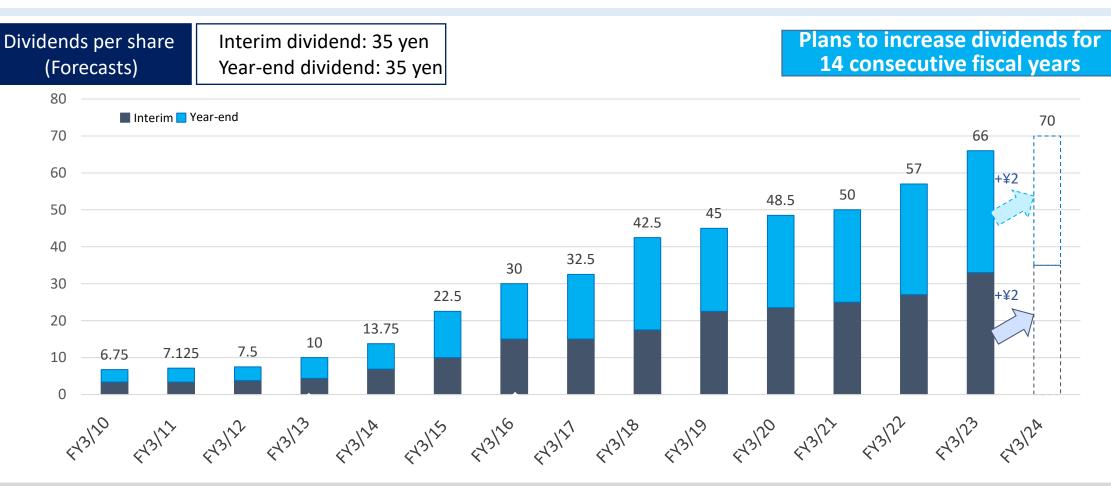






FY3/24 Dividend Forecast





We will continue to make investments for sustainable growth while securing liquidity on hand and maintaining stable financial base. Our basic dividend policy is to return profits to shareholders through the flexible acquisition of treasury stock, with the aim of continuing the trend of stable dividend increases.

Efforts in Addressing ESG Challenges



JCU aims to become a global company that continues to grow in a sustainable fashion by addressing ESG challenges through its business activities.

Environmental



Development of environmentally responsible products

- Stamp type plating process equipment and chemicals
- Eco-friendly chemical nickel plating process
- Eco-friendly decorative copper sulfate plating process



CO2 emissions (non-consolidated)

<u>1,057 tons of CO2</u> (as of end-March 2023)

* Down 27% from those in FY3/14

Social



Ratio of female managers (non-consolidated)

11.3% (in End-FY3/23)



ISO 9001 certified production sites in Japan and overseas

12 sites in 7 countries (as of end-March 2023)

* Japan, China, Taiwan, South Korea, Thailand, Vietnam, and Mexico

Governance



Corporate governance structure

- Number of Directors
 Internal: 6, Outside: 4 (including 1 female)
- Number of Audit & Supervisory Board Members
 Full-time: 1, Outside: 3 (including 1 female)

Reference



- Company Profile & Opening of New Office
- Surface Treatment Technology in Future
- Major Distribution Channels
- Major Products
- Usages of Chemicals and Typical Final Products

Company Profile



Founded in : December 1957

Established on : April 1, 1968

Capital stock : 1,266 million yen

Annual sales . Non-consolidated: 12.6 billion yen / Consolidated: 27.1 billion yen

(For the fiscal year ended March 31, 2023)

Head office : TIXTOWER UENO 16F, 8-1 Higashiueno 4-chome, Taito-ku, Tokyo

Lines of . Manufacturing and sale of surface treatment chemicals, surface treatment

machines, and related materials

Representative : Masashi Kimura, Chairman and CEO

Employees : Non-consolidated: 238 / Consolidated: 544

(As of March 31, 2023)

ISO Certificates

business

ISO9001

Production Headquarters, Head Office Sales and Marketing Department, and R&D Center (JCQA-0281)

ISO14001 Production Headquarters and R&D Center (JCQA-E-0143)

Opening of New Office (Malaysia)



In Malaysia, large investments in semiconductor-related companies continue, we have begun sales of semiconductor-related surface treatment chemicals and equipment.

This is the fourth country in Southeast Asia where we have a base of operations, following Thailand, Vietnam, and Indonesia.

Company name	JCU MALAYSIA SDN. BHD.
Location	631, Jalan Seraya 3/7, Pusat Perniagaan Seraya, 09000 Kulim, Kedah
Established	September 30, 2022
Start of operations	March 13, 2023 (Opening ceremony: May 22, 2023)
Business	Production and sales of chemicals, machines, and auxiliary equipment for surface treatment



Surface Treatment Technology in Future — Electronic Components—



Target technology

Surface

treatment

technology to be

tocus

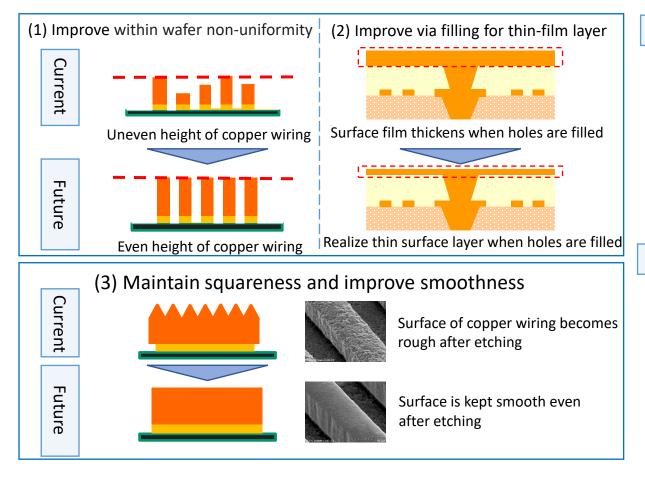
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Via Filling

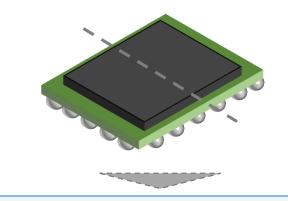
Etching

Platin,

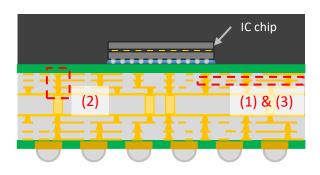
Next-generation IC-PKG boards for high-performance electronic devices, communications infrastructure, car electronics, etc.



Schematic diagram of semiconductor package board



Sectional view of semiconductor package board



Surface Treatment Technology in Future — Decoration & Function—



Target technology

Surface

treatment technology to

tocus

Eco-friendly surface treatment technology

Automotive components (front grilles, door handles, emblems, etc.) Faucet parts (showerheads, drain plugs, etc.)

(1) Restricted substance-free alternatives Processes using Cr6+ Pre-treatment Current - Etching Post-treatment - Plating Hexavalent chromium ion - Electrolytic chemical treatment considered harmful to humans **Future** Implement environmentally responsible processes thoroughly free from hexavalent chromium ion considered harmful to humans

(2) Eco-friendly decorative copper plating process



Environmentally harmful chemicals are used in manufacturing process

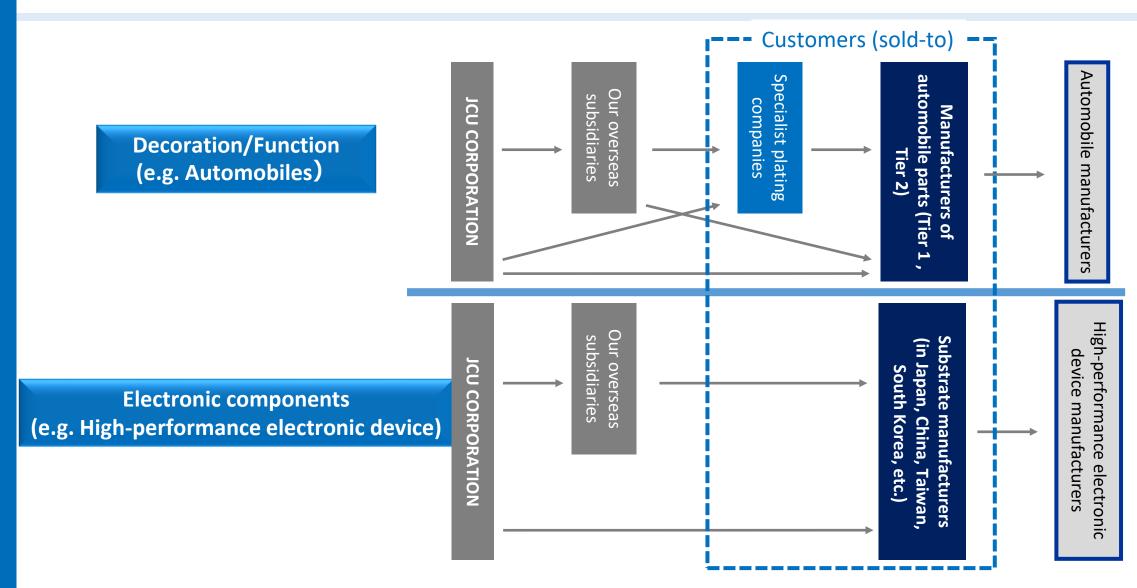


Develop a non-dye-based additive for copper plating that realizes the same performance as the conventional one, without using environmentally harmful chemicals



Major Distribution Channels





Major Products



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For decoration and function (Key chemicals)	Automotive parts (front grilles, door handles, emblems, etc.) Faucet parts (water supply equipment, showerheads, drain plugs, etc.) Construction materials (bolts, nuts, etc.)
For electronic components (Chemicals for electronic components)	PWBs (reversible and multilayer, build-up substrates, package substrates, etc.) Electronic components (lead frames, chip components, connectors, etc.) Semiconductors (silicon wafers)

Machine Business

Fully-automated surface treatment equipment	Fully-automated equipment from input of materials to completion of the plating process
Peripheral equipment	Manufacturing and sale of filtration machines and other peripheral equipment to be attached to surface treatment equipment
Automatic analytical control systems	Automatic management of plating solutions by analyzing concentrations of chemicals and adding chemicals when an insufficient level is detected
Plasma system	Etching and washing devices for PWBs as part of pre-plating processes

Usages of Chemicals and Typical Final Products



Description of term		Final products	
Chemicals for Function/decoration	Surface treatment (plating) chemicals for decorative and rust-proofing purposes such as those for providing a metal appearance and preventing rust.	Automotive parts, faucet parts and construction materials	
POP (Plating on Plastics) chemicals	Major products for key chemicals Chemicals for metal coating on plastics	(Automotive parts) Front grilles, emblems, etc. (Faucet parts) Showerheads, water faucet cocks, etc.	
Other key chemicals	Chemicals for metal coating on metallic materials such as copper and steel	(Construction materials) Screws, hinges, etc.	
Chemicals for electronic components	Plating chemicals for manufacturing PWBs, such as a circuit for electronic signals and an electrical contact for electronic components	5G-related components, data centers and other infrastructures and high-performance electronic devices	
Via filling chemicals (for PWBs/motherboards)	Copper plating chemicals for formulating interconnection onto PWBs/motherboards embedded in electronic products	(5G-related components) 5G base stations, in-vehicle PWBs, smart home	
Via filling chemicals (for semiconductor package boards)	Copper plating chemicals for formulating interconnection onto PWBs (semiconductor packages boards) for the purpose of protecting a semiconductor chip from the external environment and mounting to PWBs	appliances, etc. (Data centers and other infrastructures) Motherboards for communication servers etc. (High-performance electronic devices)	
Other	Plating chemicals for connecters and lead frames, etching chemicals for scraping unnecessary copper when formulating interconnection onto motherboards or semiconductor packages boards	Smartphones, PCs, tablets, game consoles, etc.	



This material contains current plans and forecasts of future performance of JCU CORPORATION. These plans and forecast figures are prepared by the Company based on currently available information. This material does not give any assurance or guarantee of the Company's future financial performance and actual results may differ substantially from these plans for a number of conditions or developments in the future.

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